I CLAIM:

- 1. A method of modeling a semiconductor device comprising the steps of:
- a) modeling a small signal electrical equivalent circuit for said semi conductor which includes a plurality of electrical circuit elements defining a small signal model;
- b) deriving said electrical circuit elements from a small signal excitation analysis of one or more predetermined characteristics of said semiconductor device.
- 2. The method as recited in claim 1, wherein step (b) includes deriving the electrical circuit elements from a small signal excitation analysis of the intrinsic charge within the semiconductor device.
- 3. The method as recited in claim 2, wherein step (b) further includes deriving the electrical circuit elements from a small signal excitation analysis of the electric fields within the device
- 4. The method as recited in claim 1, wherein step (b) further includes deriving the electrical circuit element from a small signal excitation analysis of the electric fields within the device.
 - 5. The method as recited in claim 2, wherein step (b) includes the following step:
- d) determining the relationships between one or more the conduction band offsets and electrical permitivities and the material composition for the materials in the semiconductor.
 - 6. The method as recited in claim 5, wherein step (d) is determined analytically.
- 7. The method as recited in claim 6, wherein step (d) is determined by fitting simulated data.
- 8. The method as recited in claim 5, further including step (e); determining the electron transport characteristics of any bulk materials in the semiconductor.

- 9. The method as recited in claim 8, further including step (f); determining the undepleted linear channel mobility.
- 10. The method as recited in claim 9, wherein step (b) is determined by material characterization.
- 11. The method as recited in claim 9, wherein step (f) is determined by physical simulation.
- 12. The method as recited in claim 9, further including step (g) determining the Schottky barrier height expressions.
- 13. The method as recited in claim 12, further including step (h) forming semiphysical equations with empirical terms for modeling one or more of the following
 characteristics: fundamental-charge control physics for sheet charge in the active
 channel as controlled by the gate terminal voltage; average centroid position of the
 sheet charge within the active channel width; position of charge partitioning boundaries
 as a function of gate, drain and source terminal voltages; bias dependence of linear
 channel mobility and surface depleted regions; bias dependence of the velocity
 saturating electric field of the channel; saturated electron velocity; electrical
 conductance within the linear region of the channel, under the gate; electrical
 conductance within the source and drain access regions.
- 14. The method as recited in claim 13, further including step (i): adjusting the empirical terms of the semi-physical equations to fit the model current-voltage (I-V) characteristics relative to measured values.
- 15. The method as recited in claim 14, further including steps (j): iteratively readjusting the empirical terms to achieve a simultaneous fit of measured capacitance voltage (C-V) and I-V characteristics.